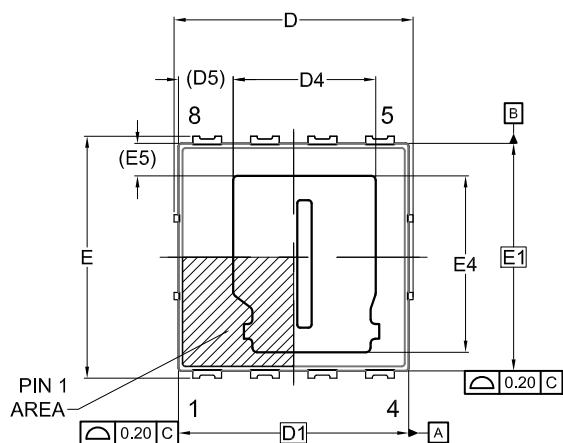


TDFNW8 8.30x8.40x0.92, 2.00P
CASE 507AR
ISSUE C

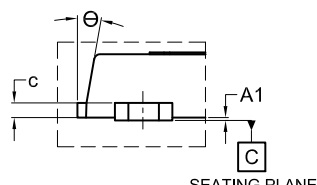
DATE 29 MAY 2024



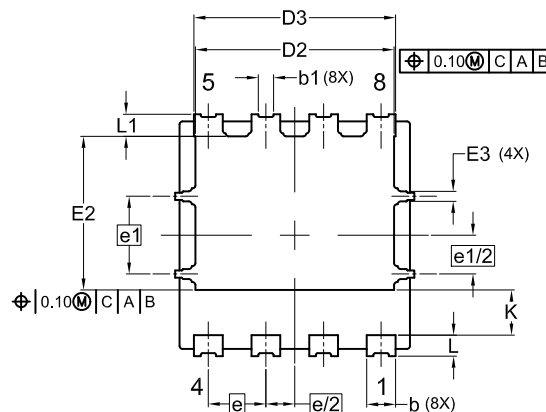
TOP VIEW



SEE DETAIL A FRONT VIEW



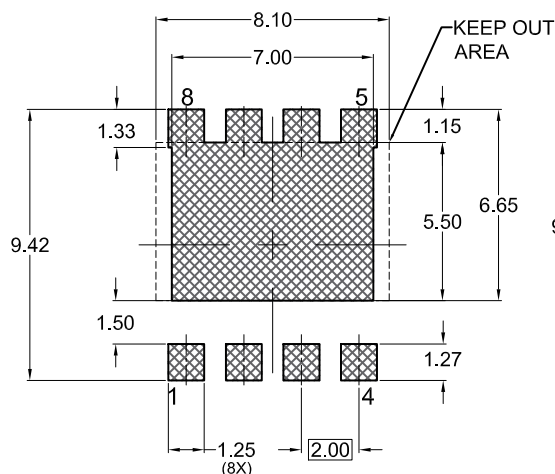
DETAIL A
(SCALE: 2X)



BOTTOM VIEW

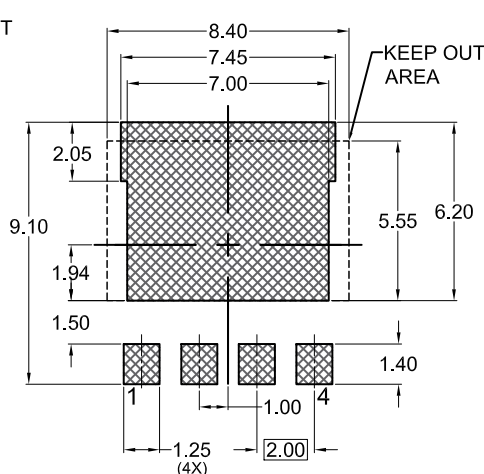
NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS.
 "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.



RECOMMENDED LAND PATTERN

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.



UNIVERSAL LAND PATTERN*

| DIM | MILLIMETERS | | |
|------|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.82 | 0.92 | 1.02 |
| A1 | 0.00 | — | 0.05 |
| b | 0.90 | 1.00 | 1.10 |
| b1 | 0.35 | 0.45 | 0.55 |
| c | 0.23 | 0.28 | 0.33 |
| D | 8.20 | 8.30 | 8.40 |
| D1 | 8.00 BSC | | |
| D2 | 6.80 | 6.90 | 7.00 |
| D3 | 6.90 | 7.00 | 7.10 |
| D4 | 4.90 | 5.05 | 5.20 |
| D5 | 1.85 REF | | |
| E | 8.30 | 8.40 | 8.50 |
| E1 | 7.90 BSC | | |
| E2 | 5.24 | 5.34 | 5.44 |
| E3 | 0.25 | 0.35 | 0.45 |
| E4 | 6.08 | 6.23 | 6.38 |
| E5 | 1.13 REF | | |
| e | 2.00 BSC | | |
| e/2 | 1.00 BSC | | |
| e1 | 2.70 BSC | | |
| e1/2 | 1.35 BSC | | |
| K | 1.50 | 1.57 | 1.70 |
| L | 0.64 | 0.74 | 0.84 |
| L1 | 0.67 | 0.77 | 0.87 |
| Θ | 0° | — | 12° |

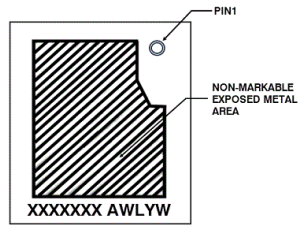
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DATE 29 MAY 2024

**GENERIC
MARKING DIAGRAM***



XXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot Code
Y = Year Code
W = Work Week Code

*This information is generic. Please refer to device data sheet for actual part marking.
Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

| | | |
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